

second high density interconnect layer for providing an electrical path from a second electronic device to a second plurality of shielded signal conductors located within the substrate.

37. (NEW) The method of claim 36, wherein the first dielectric layer includes a resin comprising an allylated polyphenylene ether, and wherein the second dielectric layer includes the resin.

38. (NEW) The method of claim 36, wherein the substrate includes a thermally conductive layer positioned about equidistantly from the first surface and the second surface of the substrate.

Remarks

Prompt and favorable examination on the merits is respectfully requested. Applicant's respectfully submit that the entire application is in condition for allowance. However, should the Examiner believe anything further is necessary in order to place the application in better condition for allowance, or if the Examiner believes that a telephone interview would be advantageous to resolve the issues presented, the Examiner is invited to contact the Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,

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